

Future of Work

Opening remarks



V. Cummings
Senior Manager, Workforce Development and EU
Projects
SEMI Europe, Brussels, Belgium

Abstract

Europe's semiconductor industry will face a talent gap of 75,000 professionals by 2030. Addressing skills shortages, attracting and retaining talent, and fostering diversity are essential to sustaining innovation and competitiveness. At the same time, global collaboration is key to building resilient supply chains and advancing technological leadership through the Pilot Lines. This session will explore practical approaches to education, workforce development, cross-border cooperation, and inclusive talent strategies to secure Europe's position in the semiconductor ecosystem.

Biography

Since joining SEMI Europe in 2023, Victoria manages projects that support workforce development, including the development of educational materials, awareness raising, and programs to improve DEI in the semiconductor sector. Currently, she oversees the European Chips Skills Academy (ECSA) and European Chips Diversity Alliance projects and is involved in several European projects related to skills development and education in microelectronics. Through these projects, Victoria contributes to the creation of targeted programs to attract and upskill talent for the most critical job shortages, assess employment trends and identify barriers to entry for underrepresented groups. Prior to entering the semiconductor industry, Victoria worked as a policy adviser for regulation on financial services and energy markets. She received a master's degree in political science from Boston University in 2018.

References

Horizon Europe ICOS : International Cooperation on Semiconductors for European Economic Resilience

F. Balestra
Director of Research
Grenoble INP-CNRS-SiNANO Institute, Grenoble,
France



Abstract

This presentation will deal with the ICOS CSA project dedicated to International Cooperation On Semiconductors. International cooperation is key for speeding up technological innovation, reducing cost by avoiding duplicated research, boosting the resilience of the semiconductor value and supply chains, and is one of the objectives of the EU Chips Act. The final ICOS results will be highlighted, including the analysis of the semiconductor economic and technological landscapes in Europe and leading semiconductor countries, the identification of the most promising emerging technologies, the proposal of areas for potential cooperation and the opportunities for bilateral or multilateral research collaborations in the fields of advanced functionalities and computing.

Biography

BALESTRA Francis, CNRS Research Director at CROMA, is Director Emeritus of the European SiNANO Institute and Chair of IEEE Electron Device Society France, and has been Director of several Research labs. He coordinated many European Projects (ICOS, NEREID, NANOFUNCTION, NANOSIL, etc.) that have represented unprecedented collaborations in Europe in the field of Nanoelectronics. He founded and organized many international Conferences, and has co-authored more than 500 publications. He is member of several European Scientific Councils, of the Advisory Committees of International Journals and of the IRDS (International Roadmap for Devices and Systems) International Roadmap Committee as representative of Europe.

References

European Pilot Lines: Aligning Strategy, Efficiency, and Implementation

S. Guttowski
Managing Director of the Research Fab
Microelectronics Germany (FMD)
Research Fab Microelectronics Germany (FMD),
Berlin, Germany



Abstract

Panel discussion

Biography

Stephan Guttowski studied electrical engineering at TU Berlin and subsequently earned a doctorate in the field of electromagnetic compatibility. This was followed by a postdoctoral position at Massachusetts Institute of Technology (MIT) in Cambridge, USA. After his return, he initially worked in the Electric Drives Research Laboratory of DaimlerChrysler AG before moving to the Fraunhofer Institute for Reliability and Microintegration IZM in 2001. At IZM, he was initially head of the Advanced System Development Group before taking over at the System Design & Integration department. From June 2017 to December 2020, he was Technology Park Manager for Heterointegration at the Research Fab Microelectronics Germany (FMD). Since January 2021, he has led the joint office of the Fraunhofer Group for Microelectronics and FMD.

References

European Pilot Lines: Aligning Strategy, Efficiency, and Implementation

D. Noguét
FAMES Pilot Line Project Coordinator
CEA-Leti, Grenoble, France



Abstract

FAMES Pilot Line

Biography

Dominique Noguét holds an engineering degree of the National Institute of Applied Sciences (INSA) in electrical engineering in 1992, and a PhD from National Polytechnic Institute of Grenoble (INPG) in 1998 (awarded best INPG PhD of the year). He started his career as a digital IC designer for telecommunication applications and then project manager in the same field. He led many projects at a national level (coordination of ANR projects) and in several European frameworks (FP5, FP6, FP7) He has been a key member of several IEEE standard groups and was subsequently elevated to the grade of IEEE Senior Member for his contributions. In parallel he held managerial positions at CEA-Leti as lab manager and department manager. In January 2023, he was appointed project manager for the French 'France 2030' flagship project NextGen on FD-SOI advanced nodes and reports to CEA-Leti's CEO since then. He is currently the project coordinator of the Chips JU FAMES Pilot Line. Dominique has authored or co-authored more than 100 scientific papers (several best paper awards), book chapters and holds 20 patents.

References

European Pilot Lines: Aligning Strategy, Efficiency, and Implementation

I. Asselberghs
Strategic Development Director
IMEC, Leuven, Belgium



Abstract

Coming Soon

Biography

Coming Soon

References

European Pilot Lines: Aligning Strategy, Efficiency, and Implementation

V. Pruneri
Director
PixEurope, Barcelona, Spain



Abstract

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Biography

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References